

# NCV4264-2

## Low $I_Q$ Low Dropout Linear Regulator

The NCV4264-2 is functionally and pin for pin compatible with NCV4264 with a lower quiescent current consumption. Its output stage supplies 150 mA with  $\pm 2.0\%$  output voltage accuracy.

Maximum dropout voltage is 500 mV at 100 mA load current.

It is internally protected against 45 V input transients, input supply reversal, output overcurrent faults, and excess die temperature. No external components are required to enable these features.

### Features

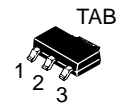
- 5.0 V Fixed Output
- $\pm 2.0\%$  Output Accuracy, Over Full Temperature Range
- 60  $\mu\text{A}$  Maximum Quiescent Current at  $I_{\text{OUT}} = 100 \mu\text{A}$
- 500 mV Maximum Dropout Voltage at 100 mA Load Current
- Wide Input Voltage Operating Range of 5.5 V to 45 V
- AEC-Q100 Qualified
- Internal Fault Protection
  - ◆ -42 V Reverse Voltage
  - ◆ Short Circuit/Overcurrent
  - ◆ Thermal Overload
- NCV Prefix for Automotive and Other Applications Requiring Site and Control Changes
- This is a Pb-Free Device



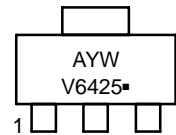
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### MARKING DIAGRAM

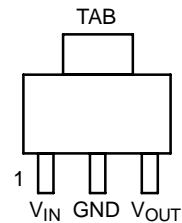


**SOT-223  
ST SUFFIX  
CASE 318E**



A = Assembly Location  
Y = Year  
W = Work Week  
▪ = Pb-Free Package

### PIN CONNECTIONS



(Top View)

### ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 7 of this data sheet.

# NCV4264-2

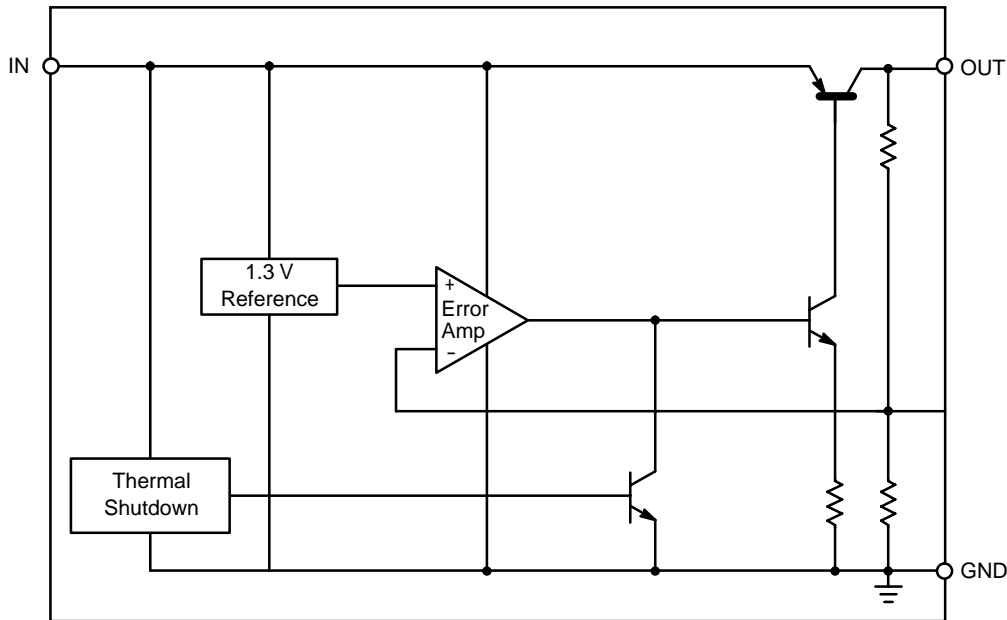


Figure 1. Block Diagram

## PIN FUNCTION DESCRIPTION

Pin No.	Symbol	Function
1	$V_{IN}$	Unregulated input voltage; 5.5 V to 45 V.
2	GND	Ground; substrate.
3	$V_{OUT}$	Regulated output voltage; collector of the internal PNP pass transistor.
TAB	GND	Ground; substrate and best thermal connection to the die.

## OPERATING RANGE

Rating	Symbol	Min	Max	Unit
$V_{IN}$ , DC Input Operating Voltage	$V_{IN}$	5.5	+45	V
Junction Temperature Operating Range	$T_J$	-40	+150	°C

## MAXIMUM RATINGS

Rating	Symbol	Min	Max	Unit
$V_{IN}$ , DC Input Voltage	$V_{IN}$	-42	+45	V
$V_{OUT}$ , DC Voltage	$V_{OUT}$	-0.3	+16	V
Storage Temperature	$T_{stg}$	-55	+150	°C
Moisture Sensitivity Level	MSL	1		-
ESD Capability, Human Body Model (Note 1)	$V_{ESDHB}$	4000	-	V
ESD Capability, Machine Model (Note 1)	$V_{ESDMIM}$	200	-	V
Lead Temperature Soldering Reflow (SMD Styles Only), Lead Free (Note 2)	$T_{slid}$	-	265 pk	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

- This device series incorporates ESD protection and is tested by the following methods:  
ESD HBM tested per AEC-Q100-002 (EIA/JESD22-A 114C)  
ESD MM tested per AEC-Q100-003 (EIA/JESD22-A 115C)
- Lead Free, 60 sec – 150 sec above 217°C, 40 sec max at peak.

# NCV4264-2

## THERMAL RESISTANCE

Parameter	Symbol	Min	Max	Unit
Junction-to-Ambient	SOT-223 $R_{\theta JA}$	-	99 (Note 3)	$^{\circ}\text{C}/\text{W}$
Junction-to-Case	SOT-223 $R_{\theta JC}$	-	17	

## ELECTRICAL CHARACTERISTICS ( $V_{IN} = 13.5\text{ V}$ , $T_J = -40^{\circ}\text{C}$ to $+150^{\circ}\text{C}$ , unless otherwise noted.)

Characteristic	Symbol	Test Conditions	Min	Typ	Max	Unit
Output Voltage	$V_{OUT}$	$5.0\text{ mA} \leq I_{OUT} \leq 50\text{ mA}$ (Note 4) $9.0\text{ V} \leq V_{IN} \leq 16\text{ V}$	4.900	5.000	5.100	V
Output Voltage	$V_{OUT}$	$5.0\text{ mA} \leq I_{OUT} \leq 100\text{ mA}$ (Note 4) $6.0\text{ V} \leq V_{IN} \leq 21\text{ V}$	4.850	5.000	5.150	V
Line Regulation	$\Delta V_{OUT}$ vs. $V_{IN}$	$I_{OUT} = 1.0\text{ mA}$ $6.0\text{ V} \leq V_{IN} \leq 28\text{ V}$	-30	5.0	+30	mV
Load Regulation	$\Delta V_{OUT}$ vs. $I_{OUT}$	$1.0\text{ mA} \leq I_{OUT} \leq 100\text{ mA}$ (Note 4)	-40	5.0	+40	mV
Dropout Voltage	$V_{IN} - V_{OUT}$	$I_{OUT} = 100\text{ mA}$ (Notes 4 & 5)	-	270	500	mV
Quiescent Current	$I_q$	$I_{OUT} = 100\text{ }\mu\text{A}$ $T_J = 25^{\circ}\text{C}$ $T_J = -40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$ $T_J = -40^{\circ}\text{C}$ to $150^{\circ}\text{C}$	-	33	55	$\mu\text{A}$
Active Ground Current	$I_{G(ON)}$	$I_{OUT} = 50\text{ mA}$ (Note 4)	-	1.5	4.0	mA
Power Supply Rejection	PSRR	$V_{RIPPLE} = 0.5\text{ V}_{P-P}$ , $F = 100\text{ Hz}$	-	67	-	dB
Output Capacitor for Stability	$C_{OUT}$ ESR	$I_{OUT} = 0.1\text{ mA}$ to $100\text{ mA}$ (Notes 4)	10	-	-	$\mu\text{F}$ $\Omega$

## PROTECTION

Current Limit	$I_{OUT(LIM)}$	$V_{OUT} = 4.5\text{ V}$ (Note 4)	150	-	500	mA
Short Circuit Current Limit	$I_{OUT(SC)}$	$V_{OUT} = 0\text{ V}$ (Note 4)	40	-	500	mA
Thermal Shutdown Threshold	$T_{TSD}$	(Note 6)	150	-	200	$^{\circ}\text{C}$

- 1 oz., 100 mm<sup>2</sup> copper area.
- Use pulse loading to limit power dissipation.
- Dropout voltage =  $(V_{IN} - V_{OUT})$ , measured when the output voltage has dropped 100 mV relative to the nominal value obtained with  $V_{IN} = 13.5\text{ V}$ .
- Not tested in production. Limits are guaranteed by design.

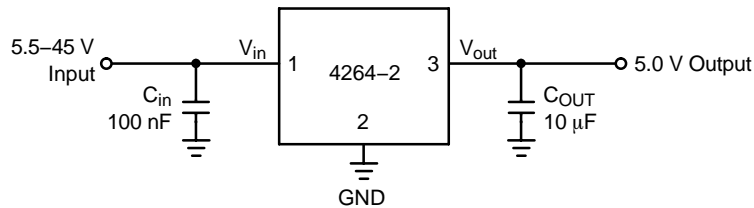


Figure 2. Applications Circuit

# NCV4264-2

## TYPICAL CHARACTERISTIC CURVES

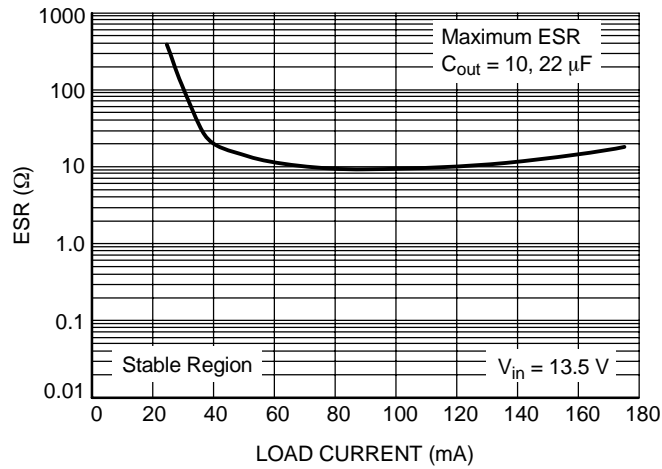


Figure 3. NCV4264-2 ESR Characterization

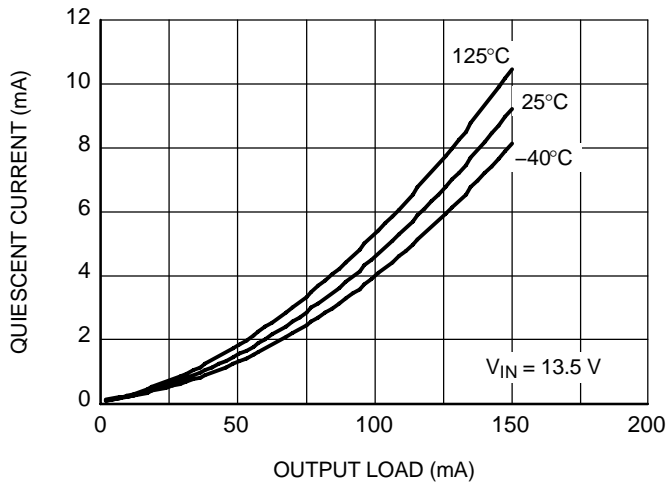


Figure 4. Quiescent Current vs. Output Load

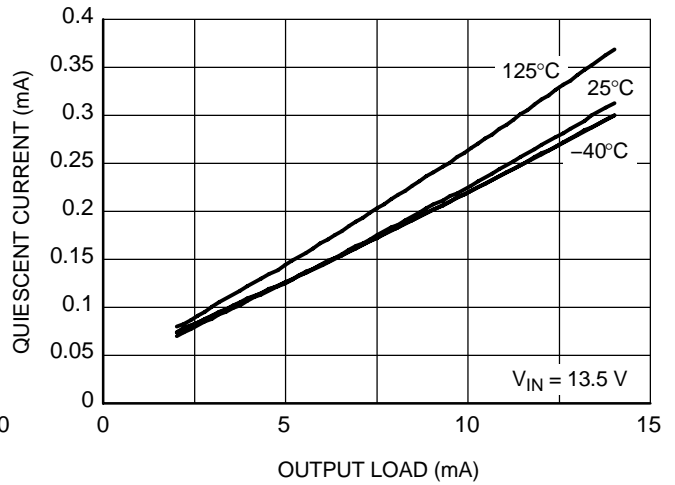


Figure 5. Quiescent Current vs. Output Load (Light Load)

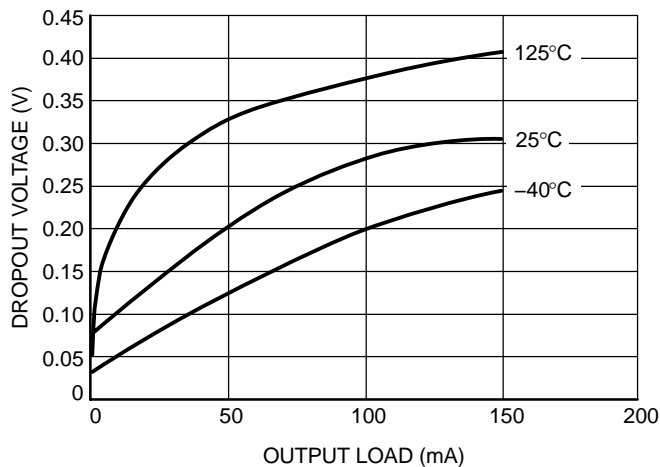


Figure 6. Dropout Voltage vs. Output Load

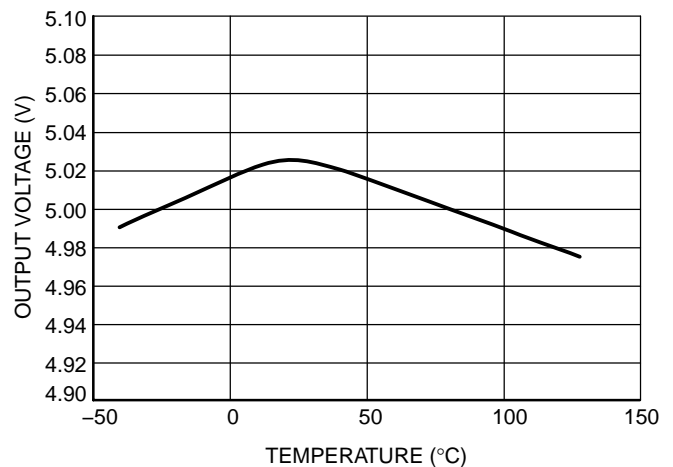


Figure 7. Output Voltage vs. Temperature

# NCV4264-2

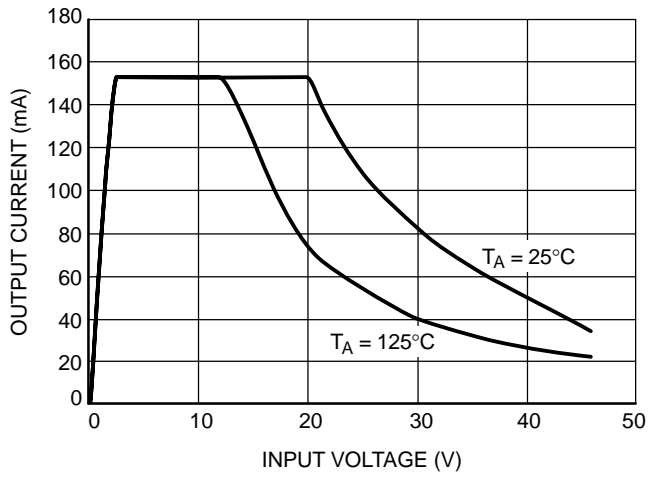


Figure 8. Output Current vs. Input Voltage

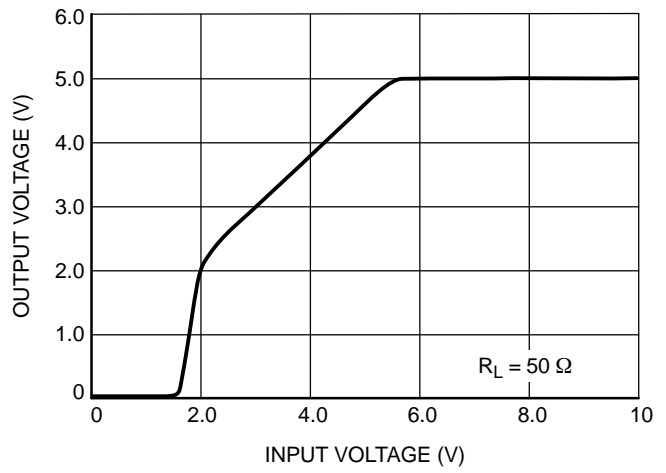


Figure 9. Input Voltage vs. Output Voltage

**Circuit Description**

The NCV4264–2 is functionally and pin for pin compatible with NCV4264 with a lower quiescent current consumption. Its output stage supplies 150 mA with ±2.0% output voltage accuracy.

Maximum dropout voltage is 500 mV at 100 mA load current. It is internally protected against 60 V input transients, input supply reversal, output overcurrent faults, and excess die temperature. No external components are required to enable these features.

**Regulator**

The error amplifier compares the reference voltage to a sample of the output voltage (V<sub>OUT</sub>) and drives the base of a PNP series pass transistor by a buffer. The reference is a bandgap design to give it a temperature–stable output. Saturation control of the PNP is a function of the load current and input voltage. Oversaturation of the output power device is prevented, and quiescent current in the ground pin is minimized.

**Regulator Stability Considerations**

The input capacitor C<sub>I1</sub> in Figure 2 is necessary for compensating input line reactance. Possible oscillations caused by input inductance and input capacitance can be damped by using a resistor of approximately 1 Ω in series with C<sub>I2</sub>. The output or compensation capacitor, C<sub>OUT</sub> helps determine three main characteristics of a linear regulator: startup delay, load transient response and loop stability. The capacitor value and type should be based on cost, availability, size and temperature constraints. The aluminum electrolytic capacitor is the least expensive solution, but, if the circuit operates at low temperatures (–25°C to –40°C), both the value and ESR of the capacitor will vary considerably. The capacitor manufacturer’s data sheet usually provides this information. The value for the output capacitor C<sub>OUT</sub> shown in Figure 2 should work for most applications; however, it is not necessarily the optimized solution. Stability is guaranteed at values C<sub>Q</sub> ≥ 10 μF and an ESR ≤ 9 Ω within the operating temperature range. Actual limits are shown in a graph in the Typical Performance Characteristics section.

**Calculating Power Dissipation in a Single Output Linear Regulator**

The maximum power dissipation for a single output regulator (Figure 3) is:

$$P_{D(max)} = [V_{IN(max)} - V_{OUT(min)}] * I_{Q(max)} + V_{I(max)} * I_Q \tag{eq. 1}$$

Where:

V<sub>IN(max)</sub> is the maximum input voltage,

V<sub>OUT(min)</sub> is the minimum output voltage,

I<sub>Q(max)</sub> is the maximum output current for the application, and I<sub>Q</sub> is the quiescent current the regulator consumes at I<sub>Q(max)</sub>. Once the value of P<sub>D(max)</sub> is known, the maximum permissible value of R<sub>θJA</sub> can be calculated:

$$R_{\theta JA} = \frac{(150^{\circ}C - T_A)}{P_D} \tag{eq. 2}$$

The value of R<sub>θJA</sub> can then be compared with those in the package section of the data sheet. Those packages with R<sub>θJA</sub>’s less than the calculated value in Equation 2 will keep the die temperature below 150°C. In some cases, none of the packages will be sufficient to dissipate the heat generated by the IC, and an external heat sink will be required. The current flow and voltages are shown in the Measurement Circuit Diagram.

**Heat Sinks**

A heat sink effectively increases the surface area of the package to improve the flow of heat away from the IC and into the surrounding air. Each material in the heat flow path between the IC and the outside environment will have a thermal resistance. Like series electrical resistances, these resistances are summed to determine the value of R<sub>θJA</sub>:

$$R_{\theta JA} = R_{\theta JC} + R_{\theta CS} + R_{\theta SA} \tag{eq. 3}$$

Where:

R<sub>θJC</sub> = the junction–to–case thermal resistance,

R<sub>θCS</sub> = the case–to–heat sink thermal resistance, and

R<sub>θSA</sub> = the heat sink–to–ambient thermal resistance.

R<sub>θJA</sub> appears in the package section of the data sheet. Like R<sub>θJA</sub>, it too is a function of package type. R<sub>θCS</sub> and R<sub>θSA</sub> are functions of the package type, heat sink and the interface between them. These values appear in data sheets of heat sink manufacturers. Thermal, mounting, and heat sinking are discussed in the ON Semiconductor application note AN1040/D, available on the ON Semiconductor Website.

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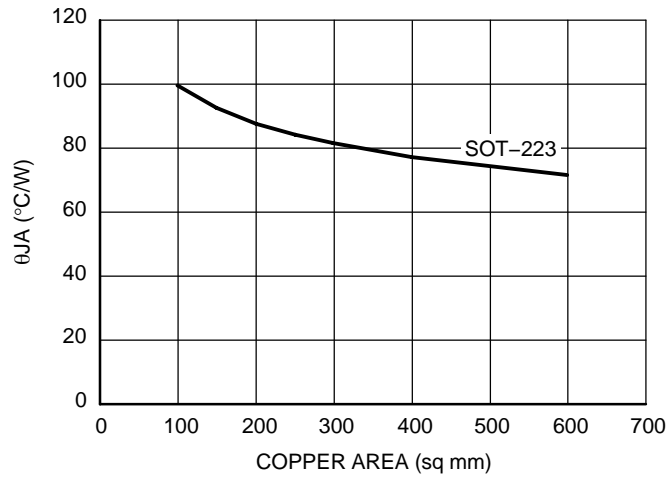


Figure 10.

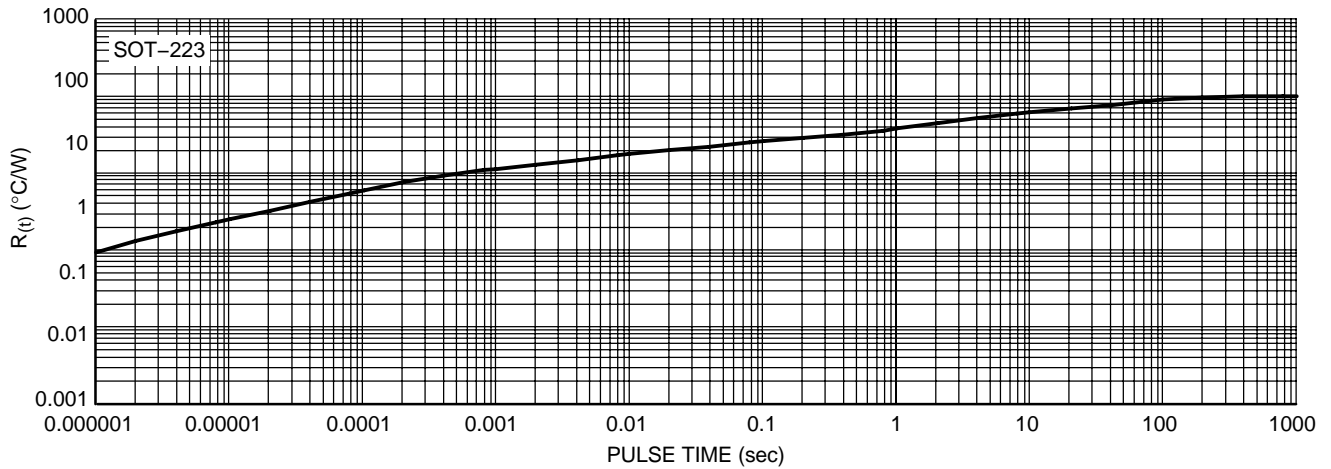


Figure 11.

## ORDERING INFORMATION

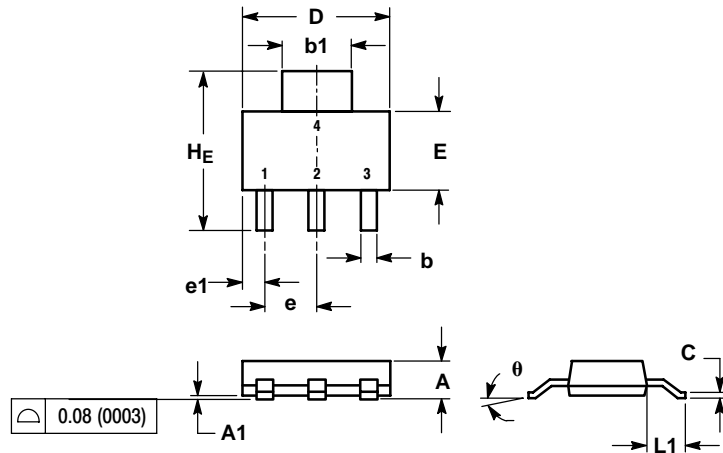
Device	Package	Shipping†
NCV4264-2ST50T3G	SOT-223 (Pb-Free)	4000 / Tape & Reel

† For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

# NCV4264-2

## PACKAGE DIMENSIONS

SOT-223 (TO-261)  
ST SUFFIX  
CASE 318E-04  
ISSUE L

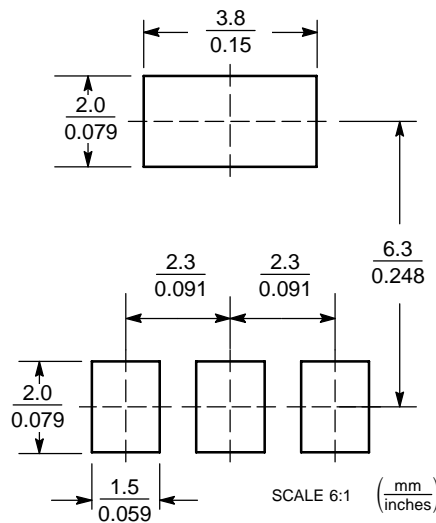


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	1.50	1.63	1.75	0.060	0.064	0.068
A1	0.02	0.06	0.10	0.001	0.002	0.004
b	0.60	0.75	0.89	0.024	0.030	0.035
b1	2.90	3.06	3.20	0.115	0.121	0.126
c	0.24	0.29	0.35	0.009	0.012	0.014
D	6.30	6.50	6.70	0.249	0.256	0.263
E	3.30	3.50	3.70	0.130	0.138	0.145
e	2.20	2.30	2.40	0.087	0.091	0.094
e1	0.85	0.94	1.05	0.033	0.037	0.041
L1	1.50	1.75	2.00	0.060	0.069	0.078
HE	6.70	7.00	7.30	0.264	0.276	0.287
θ	0°	-	10°	0°	-	10°

### SOLDERING FOOTPRINT\*



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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